

Abstracts

Low Cost MMIC Insertion Using Thick Film Processing (1987 [MCS])

A. Bettner, B. Hundley and P. Salisbury. "Low Cost MMIC Insertion Using Thick Film Processing (1987 [MCS])." 1987 Microwave and Millimeter-Wave Monolithic Circuits Symposium Digest 87.1 (1987 [MCS]): 131-133.

Multilayer thick-film circuits have been developed to provide single supply biasing and reactive matching to MMIC chips. The result is a method of achieving large amounts of gain at extremely low cost.

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